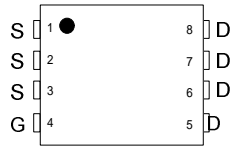
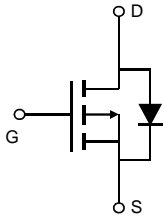
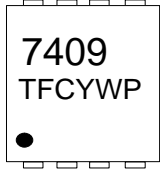


<p>30V P-Channel MOSFET</p> <p>PRODUCT SUMMARY</p> <p>V_{DS} -30V I_D (at $V_{GS}=-10V$) -32A $R_{DS(ON)}$ (at $V_{GS}=-10V$) < 15mΩ $R_{DS(ON)}$ (at $V_{GS}=-4.5V$) < 22mΩ</p> <p>100% UIS Tested 100% R_g Tested</p> <ul style="list-style-type: none"> • Trench Power αMOS Technology • Low $R_{DS(ON)}$ • Low Gate Charge • High Current Capability • RoHS and Halogen-Free Compliant <p>Applications</p> <ul style="list-style-type: none"> • DC/DC Converters in Computing • Isolated DC/DC Converters in Telecom and Industrial 	<p>PDFN3X3-8L</p>  <p>Equivalent Circuit</p>  <p>MARKING</p>  <p>Y :year code W :week code</p>
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Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted					
Parameter		Symbol	Maximum	Units	
Drain-Source Voltage		V_{DS}	-30	V	
Gate-Source Voltage		V_{GS}	± 20	V	
Continuous Drain Current ^G	$T_C=25^\circ\text{C}$	I_D	-32	A	
Pulsed Drain Current ^C		I_{DM}	-128		
Continuous Drain Current	$T_A=25^\circ\text{C}$	I_{DSM}	-16	A	
Avalanche Current ^C		I_{AS}	40	A	
Avalanche energy $L=0.1\text{mH}$ ^C		E_{AS}	80	mJ	
Power Dissipation ^B	$T_C=25^\circ\text{C}$	P_D	96	W	
Power Dissipation ^A	$T_A=25^\circ\text{C}$	P_{DSM}	3.1	W	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	$^\circ\text{C}$	
Thermal Characteristics					
Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$t \leq 10\text{s}$	$R_{\theta JA}$	30	40	$^\circ\text{C/W}$
Maximum Junction-to-Ambient ^{A D}	Steady-State		60	75	$^\circ\text{C/W}$
Maximum Junction-to-Case		$R_{\theta JC}$	1	1.3	$^\circ\text{C/W}$

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =-250μA, V _{GS} =0V	-30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-30V, V _{GS} =0V			-1	μA
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±25V			±10	uA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-1.4	-1.8	-2.0	V
I _{D(ON)}	On state drain current	V _{GS} =-10V, V _{DS} =-5V	-128			A
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =-10V, I _D =-16A		12	15	mΩ
		V _{GS} =-4.5V, I _D =-10A		18	22	mΩ
g _{FS}	Forward Transconductance	V _{DS} =-5V, I _D =-16A		-43		S
V _{SD}	Diode Forward Voltage	I _S =-1A, V _{GS} =0V		-0.7	-1	V
I _S	Maximum Body-Diode Continuous Current ^G				-32	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-15V, f=1MHz		2142		pF
C _{oss}	Output Capacitance			474		pF
C _{rss}	Reverse Transfer Capacitance			363		pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz		2.3	4.6	Ω
SWITCHING PARAMETERS						
Q _g (10V)	Total Gate Charge	V _{GS} =-10V, V _{DS} =-15V, I _D =-16A		41	58	nC
Q _g (4.5V)	Total Gate Charge			18.5	27	nC
Q _{gs}	Gate Source Charge			15		nC
Q _{gd}	Gate Drain Charge			6		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =-10V, V _{DS} =-15V, R _L =0.9Ω, R _{GEN} =3Ω		13		ns
t _r	Turn-On Rise Time			12		ns
t _{D(off)}	Turn-Off DelayTime			34		ns
t _f	Turn-Off Fall Time			18.5		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =-16A, di/dt=500A/μs		17.5		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =-16A, di/dt=500A/μs		44.5		nC

A. The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C. The Power dissipation P_{DSM} is based on R_{θJA} t ≤ 10s value and the maximum allowed junction temperature of 150° C. The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on T_{J(MAX)}=150° C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150° C. Ratings are based on low frequency and duty cycles to keep initial T_J=25° C.

D. The R_{θJA} is the sum of the thermal impedance from junction to case R_{θJC} and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=150° C. The SOA curve provides a single pulse rating.

G. The maximum current rating is package limited.

H. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

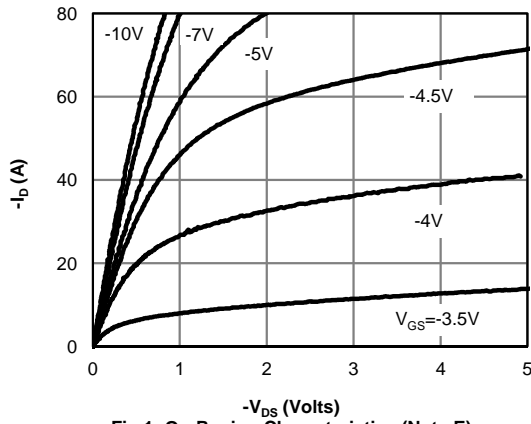


Fig 1: On-Region Characteristics (Note E)

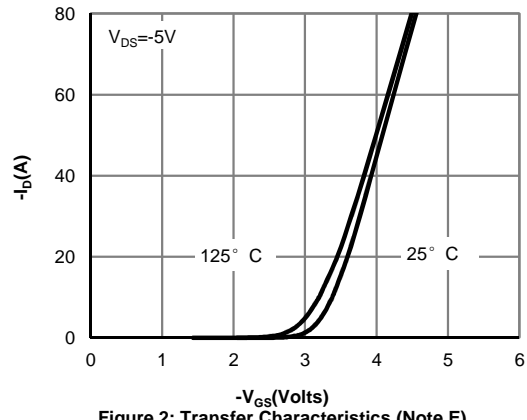


Figure 2: Transfer Characteristics (Note E)

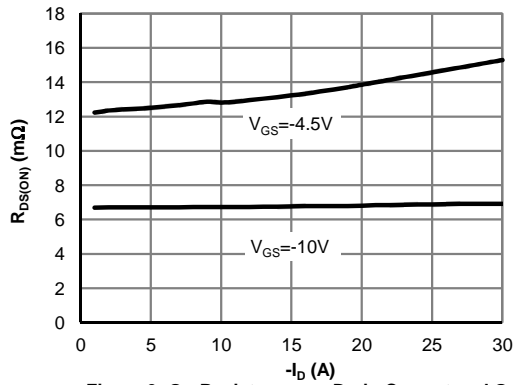


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

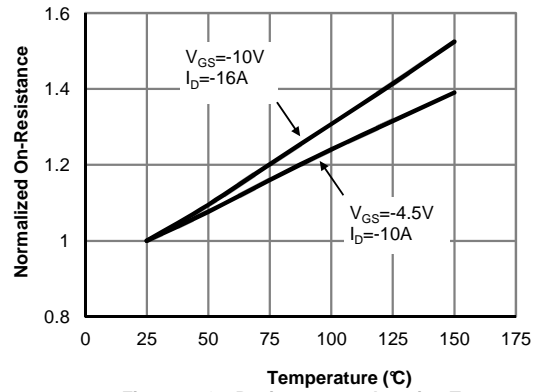


Figure 4: On-Resistance vs. Junction Temperature (Note E)

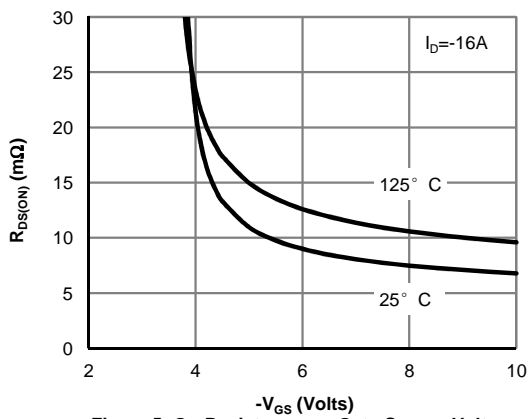


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

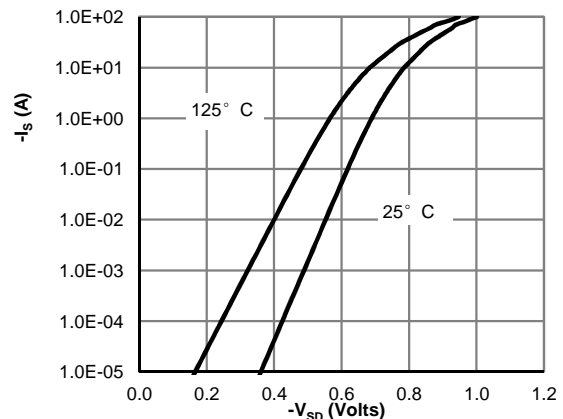


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

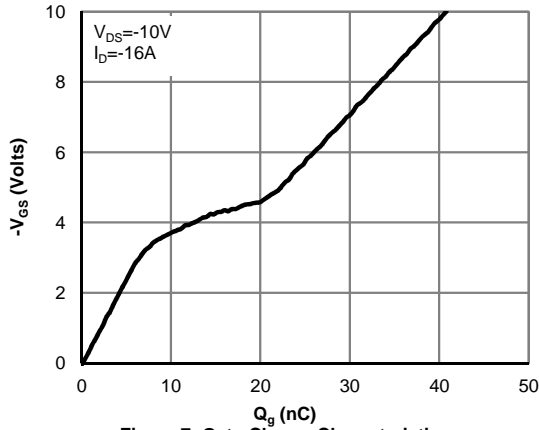


Figure 7: Gate-Charge Characteristics

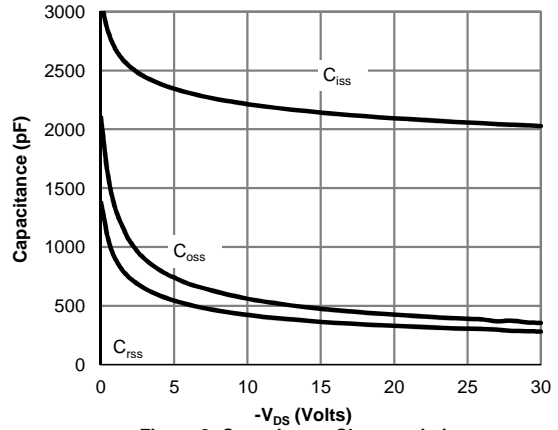


Figure 8: Capacitance Characteristics

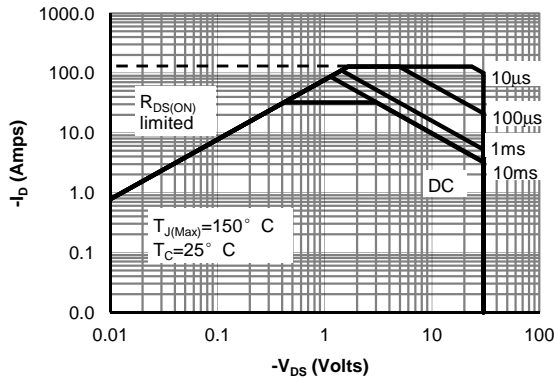


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

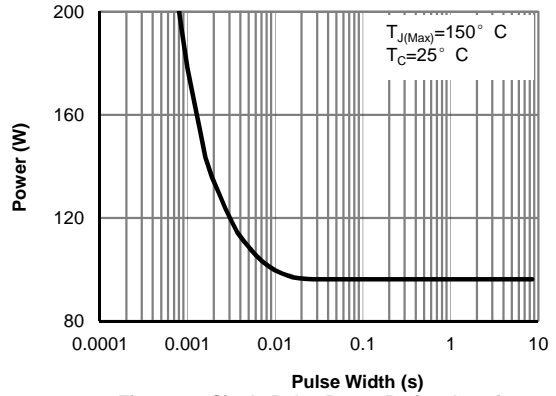


Figure 10: Single Pulse Power Rating Junction-to-Ca (Note F)

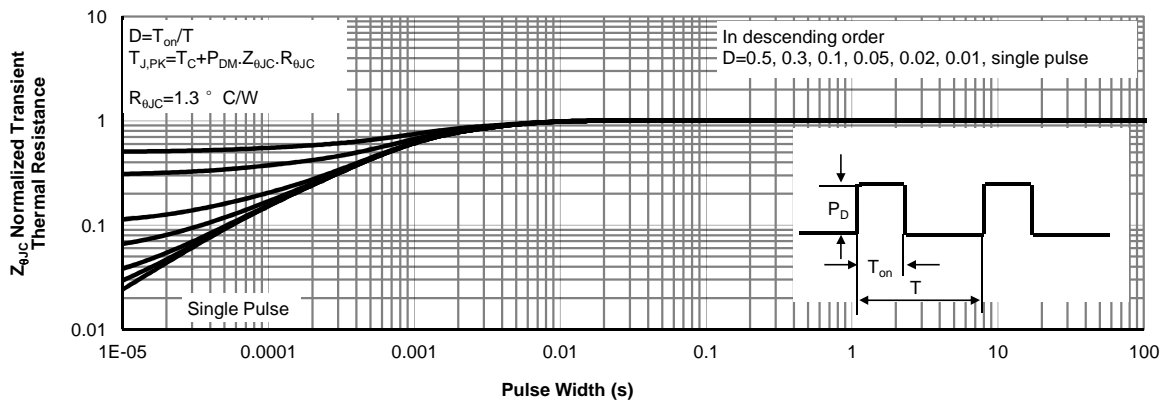


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

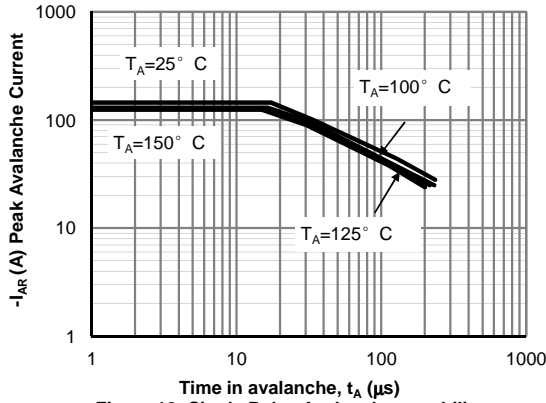


Figure 12: Single Pulse Avalanche capability (Note C)

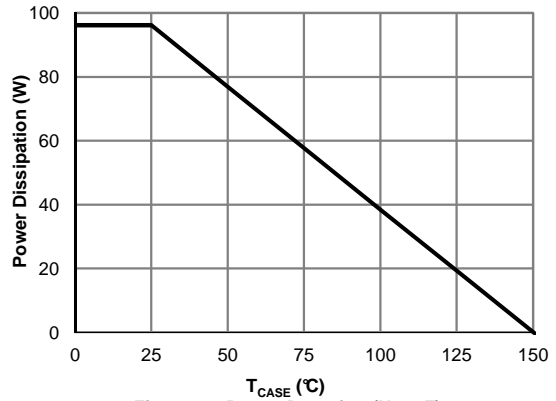


Figure 13: Power De-rating (Note F)

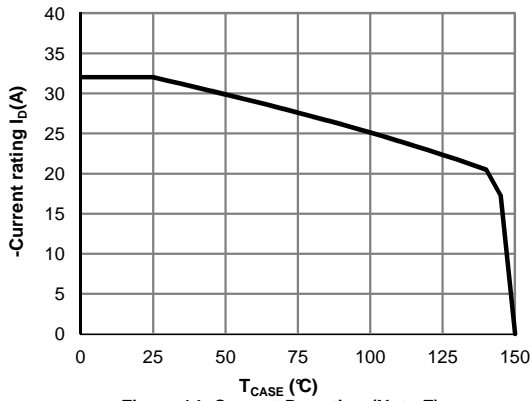


Figure 14: Current De-rating (Note F)

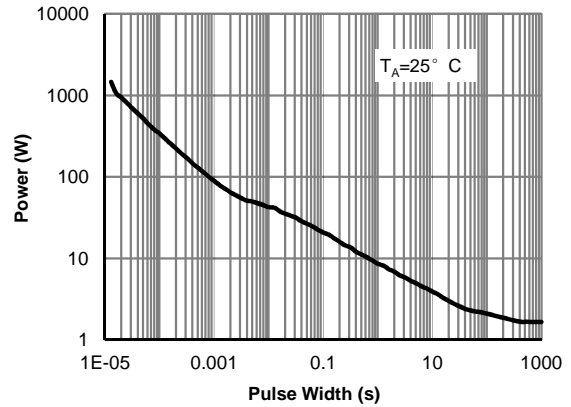


Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note H)

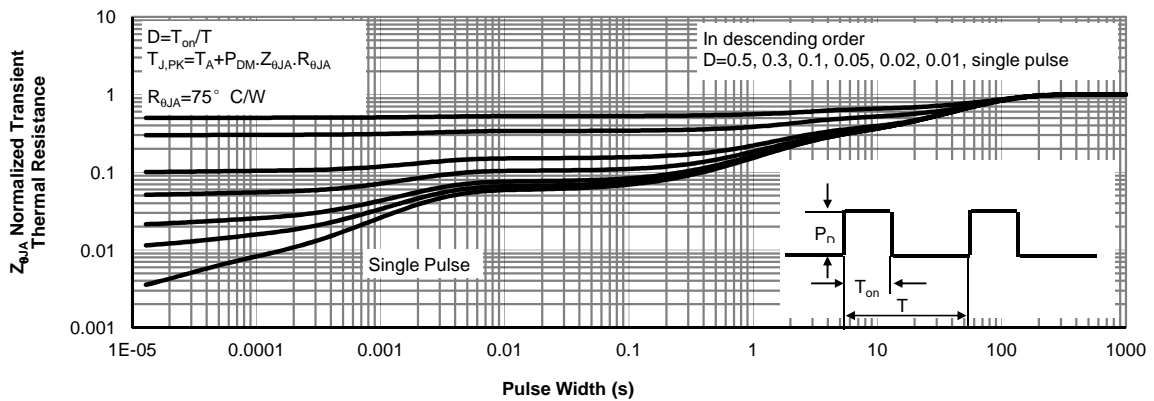
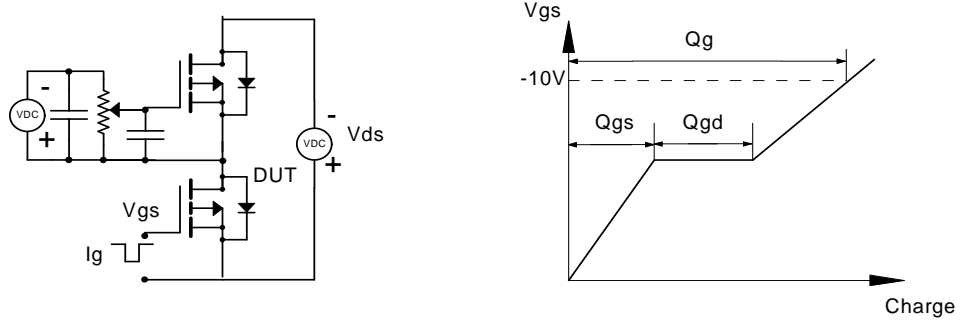
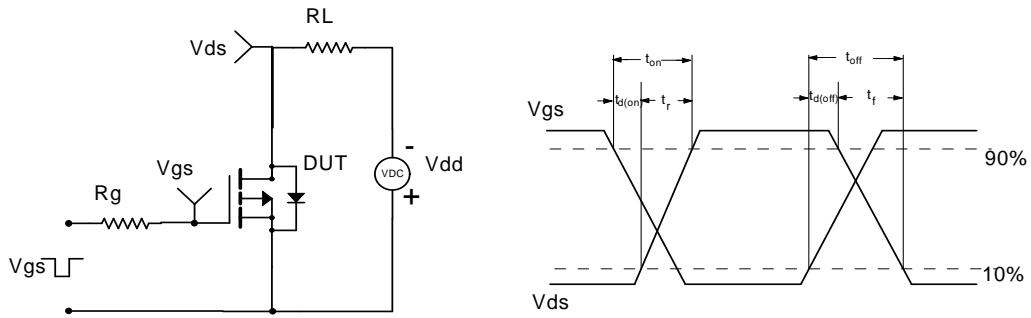


Figure 16: Normalized Maximum Transient Thermal Impedance (Note H)

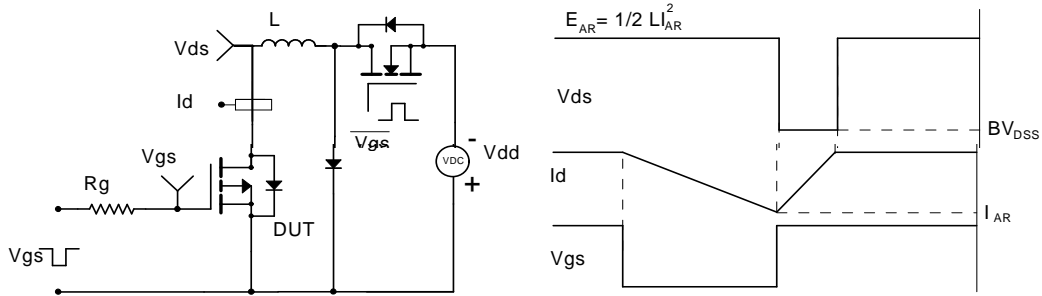
Gate Charge Test Circuit & Waveform



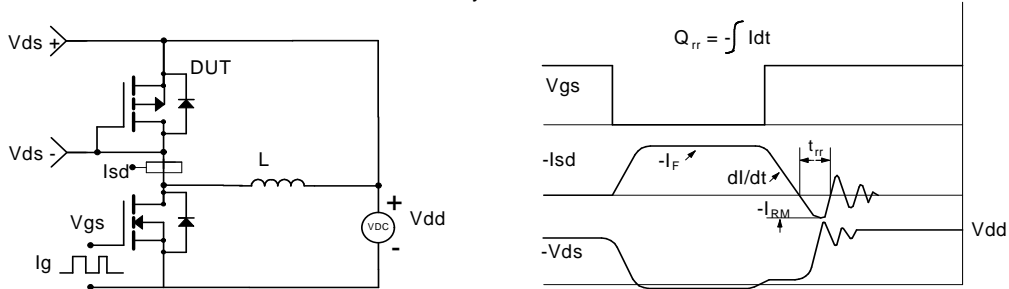
Resistive Switching Test Circuit & Waveforms



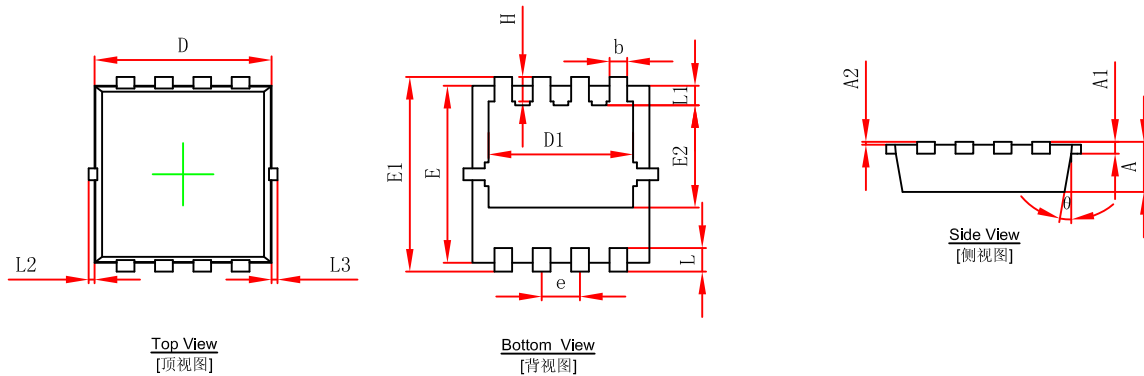
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

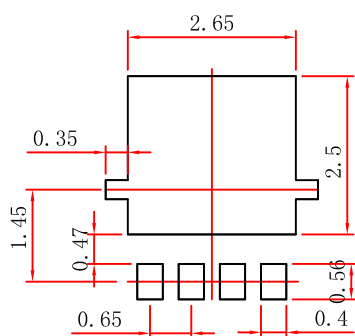


PDFNWB3.3x3.3-8L Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033
A1	0.152 REF.		0.006 REF.	
A2	0~0.05		0~0.002	
D	2.900	3.100	0.114	0.122
D1	2.300	2.600	0.091	0.102
E	2.900	3.100	0.114	0.122
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0~0.100		0~0.004	
L3	0~0.100		0~0.004	
H	0.315	0.515	0.012	0.020
θ	9°	13°	9°	13°

PDFNWB3.3x3.3-8L Suggested Pad Layout



- Note:
1. Controlling dimension: in millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$.
 3. The pad layout is for reference purposes only.